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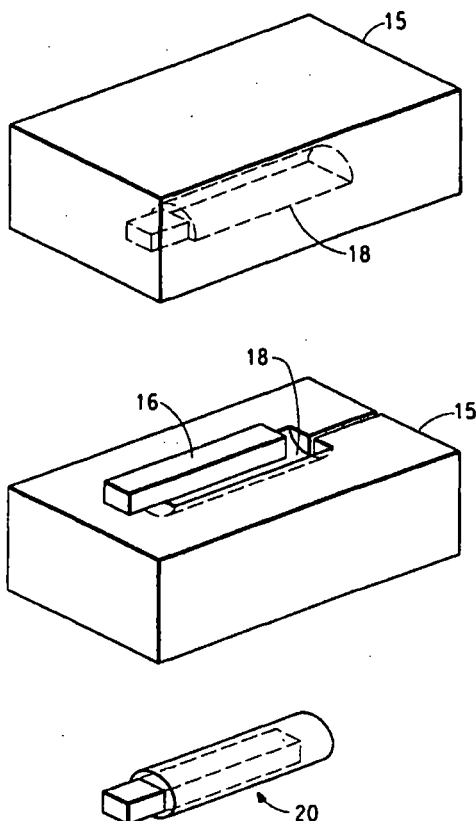
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(54) Title: ENCAPSULATION USING MICROCELLULAR FOAMED MATERIALS



(57) Abstract: Injection molding encapsulation processes for packaging an object or objects in microcellular foamed material, comprising the steps of providing a mold having a mold cavity, positioning at least one object in the mold cavity, providing a packaging material, introducing a fluid into the packaging material under conditions sufficient to produce a supercritical fluid-packaging material solution, introducing the solution into the mold cavity, and converting the solution into a microcellular foamed material. Such processes are advantageously employed in encapsulation of electronic or electrical components. Packaged objects produced therefrom may be completely or partially encapsulated.

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